

ABSTRACT OF THE DISCLOSURE

a A method and an apparatus of removing a particle from a metal ^{plug on}~~layer over~~ a substrate is disclosed. The method comprises introducing a slurry onto the metal layer and polishing the metal layer. A solution comprising hydrogen peroxide is introduced onto the metal ^{plug}~~layer~~ and at least one particle is removed from the metal ^{plug}~~layer~~.

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042390.P7832